



25A, 500V N-CHANNEL POWER MOSFET

TO-220F-3L(*Prefix :F)

Description

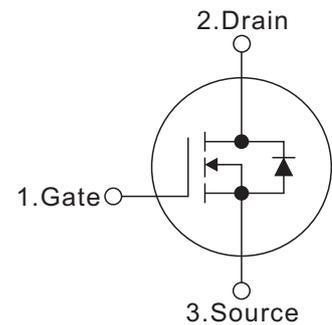
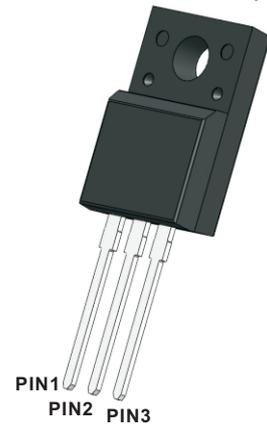
These N-channel enhanced VD mosfets, is obtained by the self-aligned planar technology which reduce the conduction loss, improve switching performance and enhance the avalanche energy. Which accords with the RoHS standard.

Features

- $R_{DS(ON)} < 0.27\Omega @ V_{GS}=10V, I_D=12.5A$
- Fast switching capability
- 100% Avalanche tested
- 100% ΔV_{DS} tested

Mechanical data

- Case: TO-220F-3L
- Approx Weight: 1.767g (0.062oz)
- Lead free finish, RoHS compliant
- Case Material: "Green" molding compound, UL flammability classification 94V-0, "Halogen-free".



Packing Marking And Ordering Information

| Device Package | Device | Marking | Packing Type | QTY Per Tube | Inner box | Per Carton |
|----------------|---------|---------|--------------|--------------|-----------|------------|
| TO-220F-3L | F25N50L | F25N50L | Tube | 50 Pcs | 2,500 Pcs | 5,000 Pcs |

Absolute Maximum Ratings (Ta=25°C, Unless Otherwise Specified)

| Parameter | Symbols | Ratings | Units |
|--|----------------|---------------------------------------|------------|
| Drain-Source Voltage | V_{DSS} | 500 | V |
| Gate-Source Voltage | V_{GSS} | ± 30 | V |
| Continuous Drain Current | I_D | 25 17.6 | A |
| | | $T_c=25^\circ C$ $T_c=100^\circ C$ | |
| Pulsed Drain Current (Note 2) | I_{DM} | 100 | A |
| Avalanche Energy Single Pulsed (Note 3) | E_{AS} | 1500 | mJ |
| Power Dissipation ($T_c = 25^\circ C$) | P_D | 300 | W |
| Operating junction and storage temperature | T_J, T_{STG} | -55 ~ +150 | $^\circ C$ |

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.
2. Repetitive Rating: Pulse width limited by maximum junction temperature.
3. L = 10mH, IAS = 17A, VDD = 50V, RG = 25 Ω , Starting TJ = 25°C

Thermal Resistance

| Parameter | Symbols | Ratings | Units |
|--|------------|---------|--------------|
| Thermal resistance, junction – case. | R_{thJC} | 4 | $^\circ C/W$ |
| Thermal resistance, junction – ambient(min. footprint) | R_{thJA} | 63 | $^\circ C/W$ |



Electrical Characteristics (Ta=25°C, Unless Otherwise Specified)

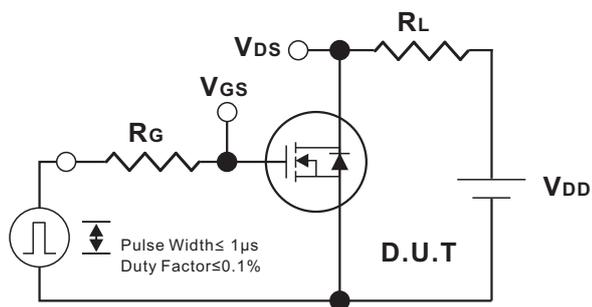
| Parameter | Symbols | Test Conditions | Min | Typ | Max | Units |
|---|--------------|--|-----|------|------|----------|
| Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{DS}=0V, I_D=250\mu A$ | 500 | | | V |
| Drain-Source Leakage Current | I_{DSS} | $V_{DS}=500V, V_{GS}=0V$ | | | 1 | μA |
| Gate- Source Leakage Current | Forward | I_{GSS} | | | 100 | nA |
| | Reverse | | | | -100 | |
| On Characteristics | | | | | | |
| Gate Threshold Voltage | $V_{GS(TH)}$ | $V_{DS}=V_{GS}, I_D=250\mu A$ | 2.0 | | 4.0 | V |
| Static Drain-Source On-State Resistance | $R_{DS(ON)}$ | $V_{GS}=10V, I_D=12.5A$ | | 0.16 | 0.27 | Ω |
| Forward Transfer Conductance | g_{fs} | $V_{DS}=15V, I_D=12.5A$ | | 20 | | S |
| Dynamic Characteristics | | | | | | |
| Input Capacitance | C_{ISS} | $V_{DS}=25V,$ $V_{GS}=0V,$ $f=1.0MHz$ | | 3200 | | pF |
| Output Capacitance | C_{OSS} | | | 338 | | pF |
| Reverse Transfer Capacitance | C_{RSS} | | | 30 | | pF |
| Gate resistance | R_G | | | 2.0 | | Ω |
| Switching Characteristics | | | | | | |
| Total Gate Charge (Note 1) | Q_G | $V_{DD}=400V, V_{GS}=10V,$ $I_D=25A, I_G=1mA$ (NOTE1,2) | | 64 | | nC |
| Gate-Source Charge | Q_{GS} | | | 17 | | nC |
| Gate-Drain Charge | Q_{GD} | | | 23 | | nC |
| Turn-On Delay Time (Note 1) | $t_{D(ON)}$ | $V_{DD}=250V, V_{GS}=10V,$ $I_D=25A, R_G=25\Omega$ (NOTE1,2) | | 37 | | ns |
| Turn-On Rise Time | t_R | | | 64 | | ns |
| Turn-Off Delay Time | $t_{D(OFF)}$ | | | 86 | | ns |
| Turn-Off Fall Time | t_F | | | 46 | | ns |
| Drain-source Diode Characteristics And Maximum Ratings | | | | | | |
| Maximum Body-Diode Continuous Current | I_S | | | | 25 | A |
| Drain-Source Diode Forward Voltage (Note 1) | V_{SD} | $I_S=25A, V_{GS}=0V$ | | | 1.4 | V |
| Reverse Recovery Time (Note 1) | t_{rr} | $I_S=25A, V_{GS}=0V,$ | | 510 | | ns |
| Reverse Recovery Charge | Q_{rr} | $di/dt=100A/\mu s$ | | 6.2 | | μC |

Notes:

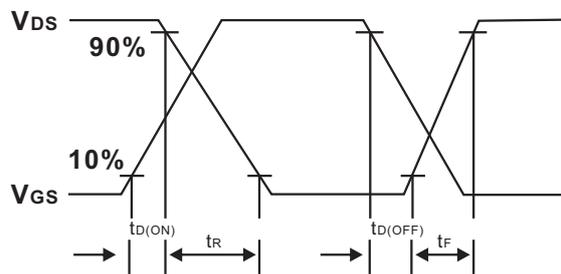
1. Pulse Test: Pulse width $\leq 300\mu s$, Duty cycle $\leq 2\%$.
2. Essentially independent of operating temperature.



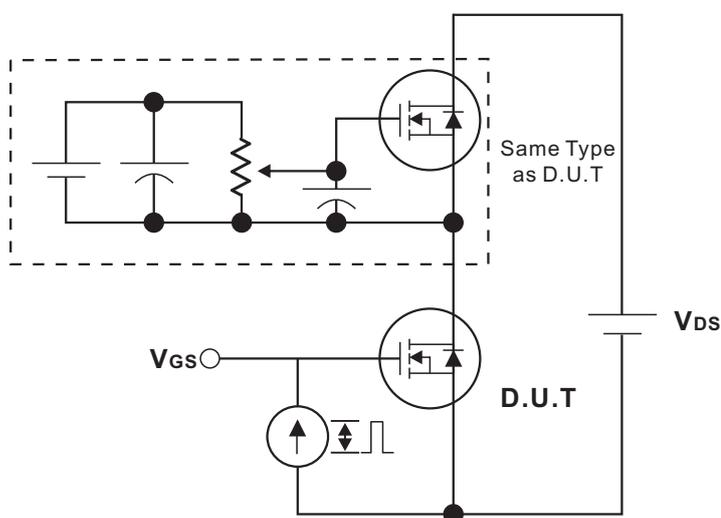
Test Circuits and waveforms



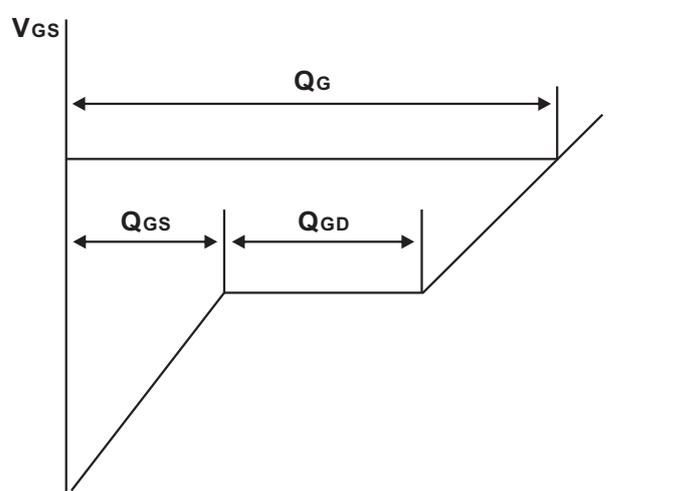
Switching Test Circuit



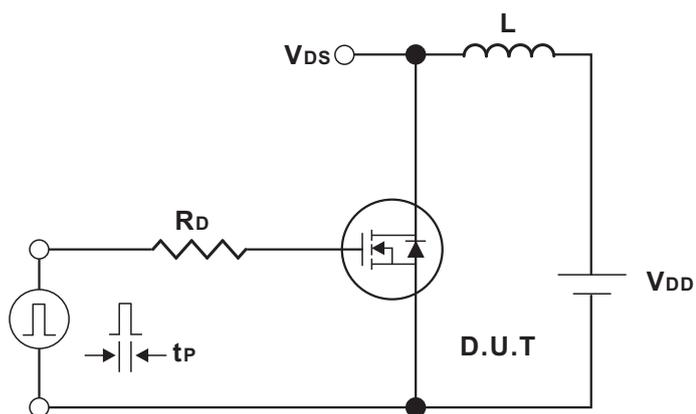
Switching Waveforms



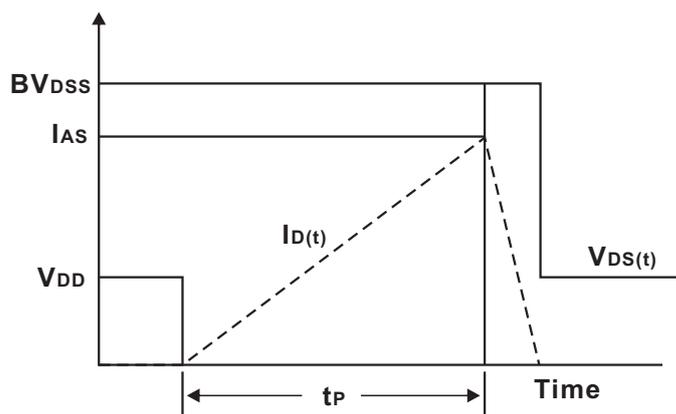
Gate Charge Test Circuit



Charge
Gate Charge Waveform



Unclamped Inductive Switching Test Circuit



Unclamped Inductive Switching Waveforms



Typical Characteristics

Fig.1 Typical Output Characteristics

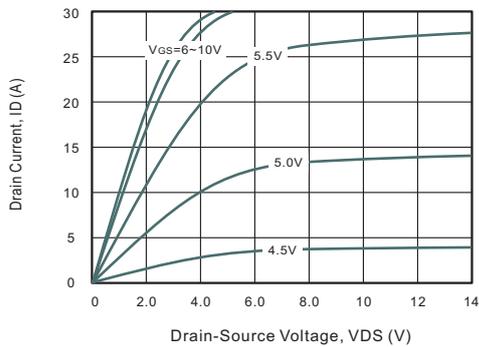


Fig.2 Power Dissipation

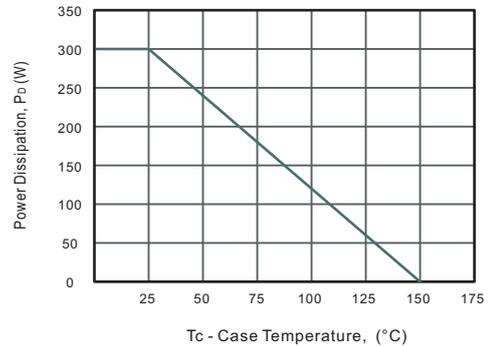


Fig.3 Drain Current Derating

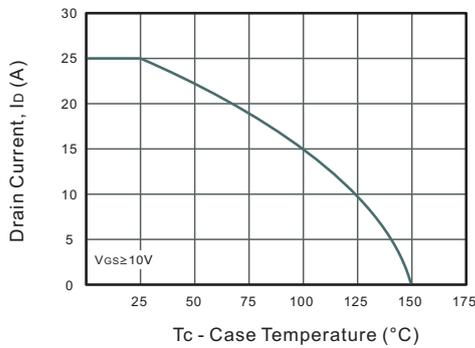


Fig.4 Drain-Source On-Resistance vs. Drain Current

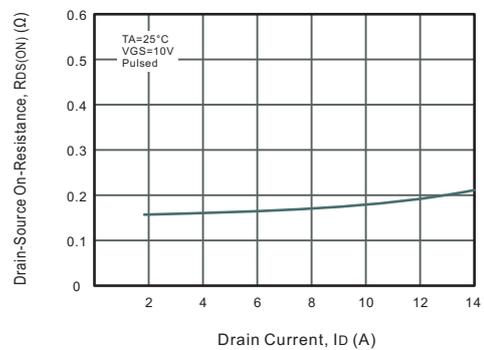


Fig.5 Gate Threshold Voltage vs. Junction Temperature

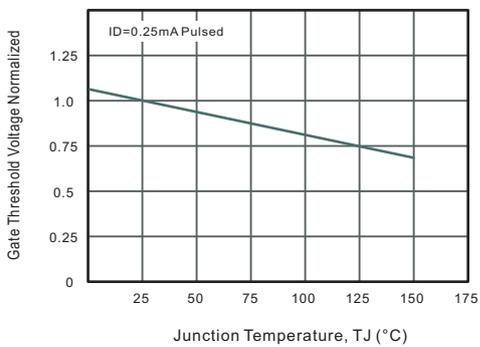


Fig.6 Body-diode Forward Characteristics

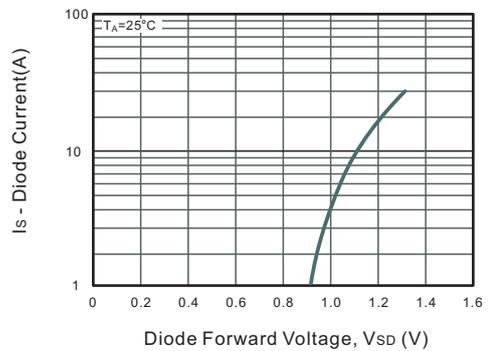


Fig.7 Drain-Source On-Resistance vs. Junction Temperature

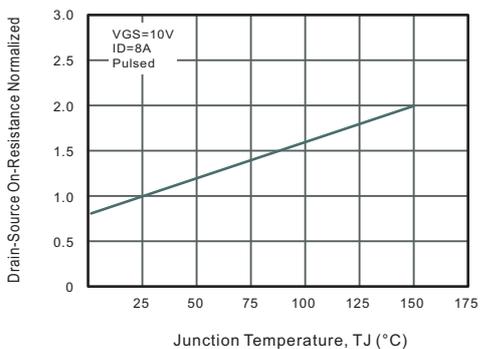
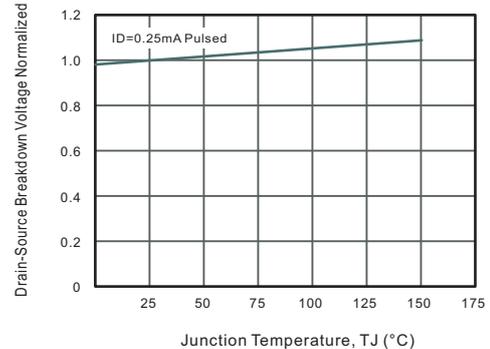


Fig.8 Breakdown Voltage vs. Junction Temperature





Typical Characteristics

Fig.9 Capacitance Characteristics

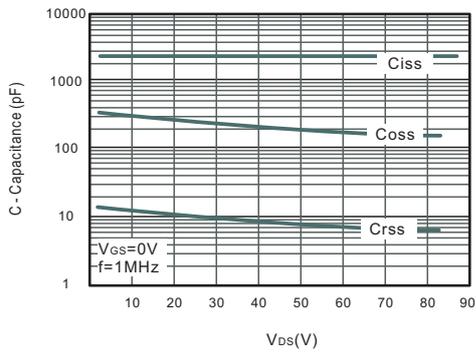


Fig.10 Gate Charge Characteristics

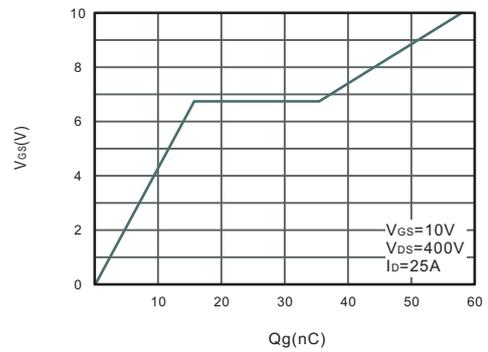


Fig.11 Safe Operating Area

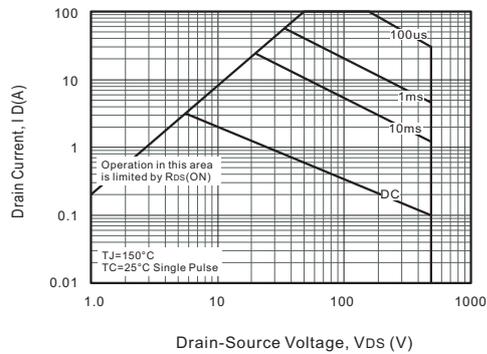
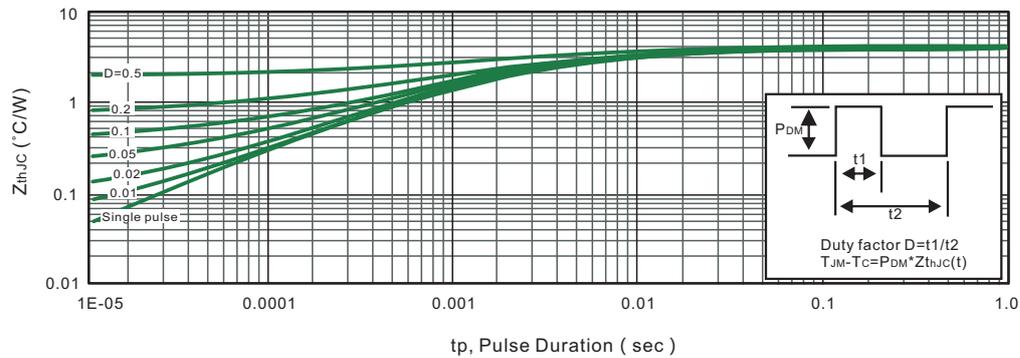


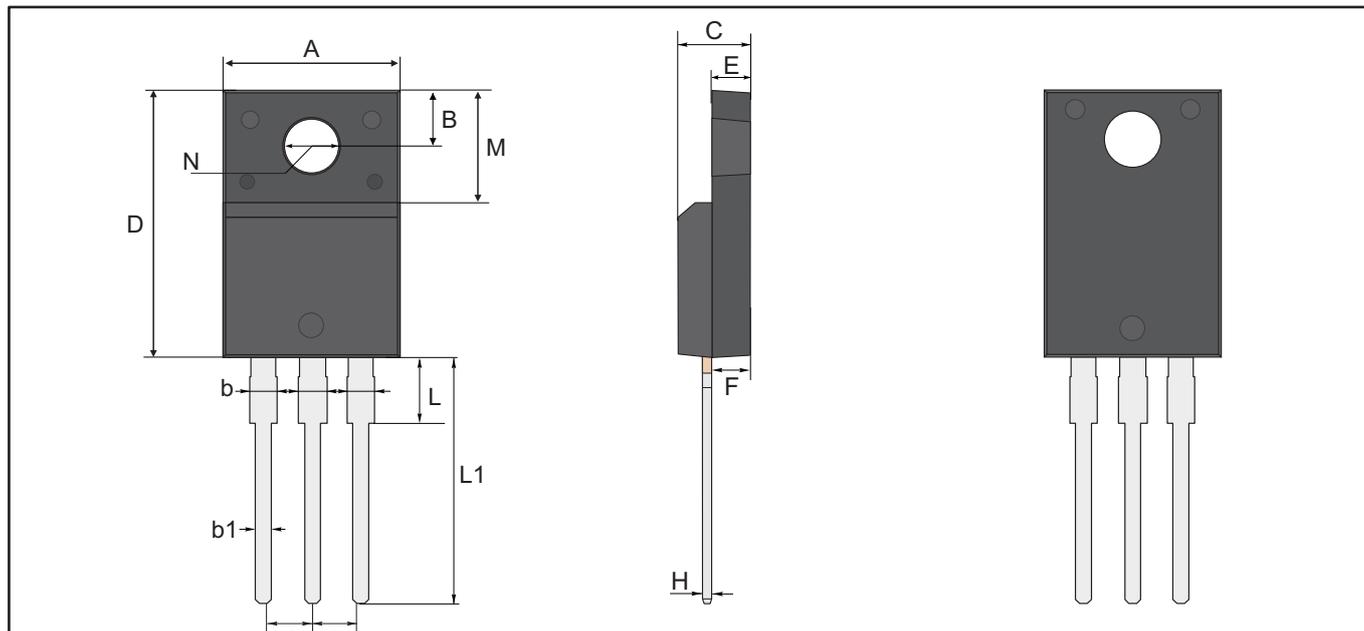
Fig.12 Max. Transient Thermal Impedance





Package Outline
Through Hole Package ; 3 leads

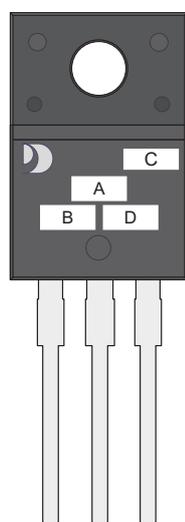
TO-220F-3L



TO-220F-3L Mechanical data

| UNIT | | A | B | b | b1 | C | D | E | F | G | H | L | L1 | M | N |
|------|-----|-------|------|------|-----|-----|-------|------|------|------|-----|------|------|------|--------------|
| mm | max | 10.28 | 3.37 | 1.44 | 0.9 | 4.9 | 16.07 | 2.74 | 2.74 | 2.64 | 0.6 | 2.85 | 13.7 | 6.98 | 3.18 typ. |
| | typ | 10.18 | 3.27 | 1.34 | 0.8 | 4.7 | 15.87 | 2.54 | 2.54 | 2.54 | 0.5 | 2.65 | 13.5 | 6.68 | |
| | min | 10.08 | 3.17 | 1.24 | 0.7 | 4.5 | 15.67 | 2.34 | 2.34 | 2.44 | 0.4 | 2.45 | 13.3 | 6.38 | |
| mil | max | 405 | 133 | 57 | 35 | 193 | 633 | 108 | 108 | 104 | 24 | 112 | 539 | 275 | 125 typ. |
| | typ | 401 | 129 | 53 | 31 | 185 | 625 | 100 | 100 | 100 | 20 | 104 | 531 | 263 | |
| | min | 397 | 125 | 49 | 28 | 177 | 617 | 92 | 92 | 96 | 16 | 96 | 524 | 251 | |

Marking Diagram



- Unmarkable Surfacea
- Marking Composition Field
- a: Ejector Pin Mark
- A: Marking Area
- B: Lot Code
- C: Additional Information
- D: Date Code (YWW)
- Y: Years(0~9)
- WW: Week



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